



Product Change Notification

Change Notification #: 114859-00
Change Title: Intel® Server System R2312WTTYSR
PCN114859-00, Product Design,
DIMM connector change
Date of Publication: August 25, 2016

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	September 9, 2016
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Server System R2312WTTYSR:

- Replaced DIMM connectors to increase gold plating thickness from 15u” to 30u” for higher durability

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA	Pre PBA	Post PBA
R2312WTTYSR	943830	J11495-004	J11495-005	G92187-366	G92187-367

PCN Revision History:

Date of Revision: August 25, 2016	Revision Number: 00	Reason: Originally Published PCN
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

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